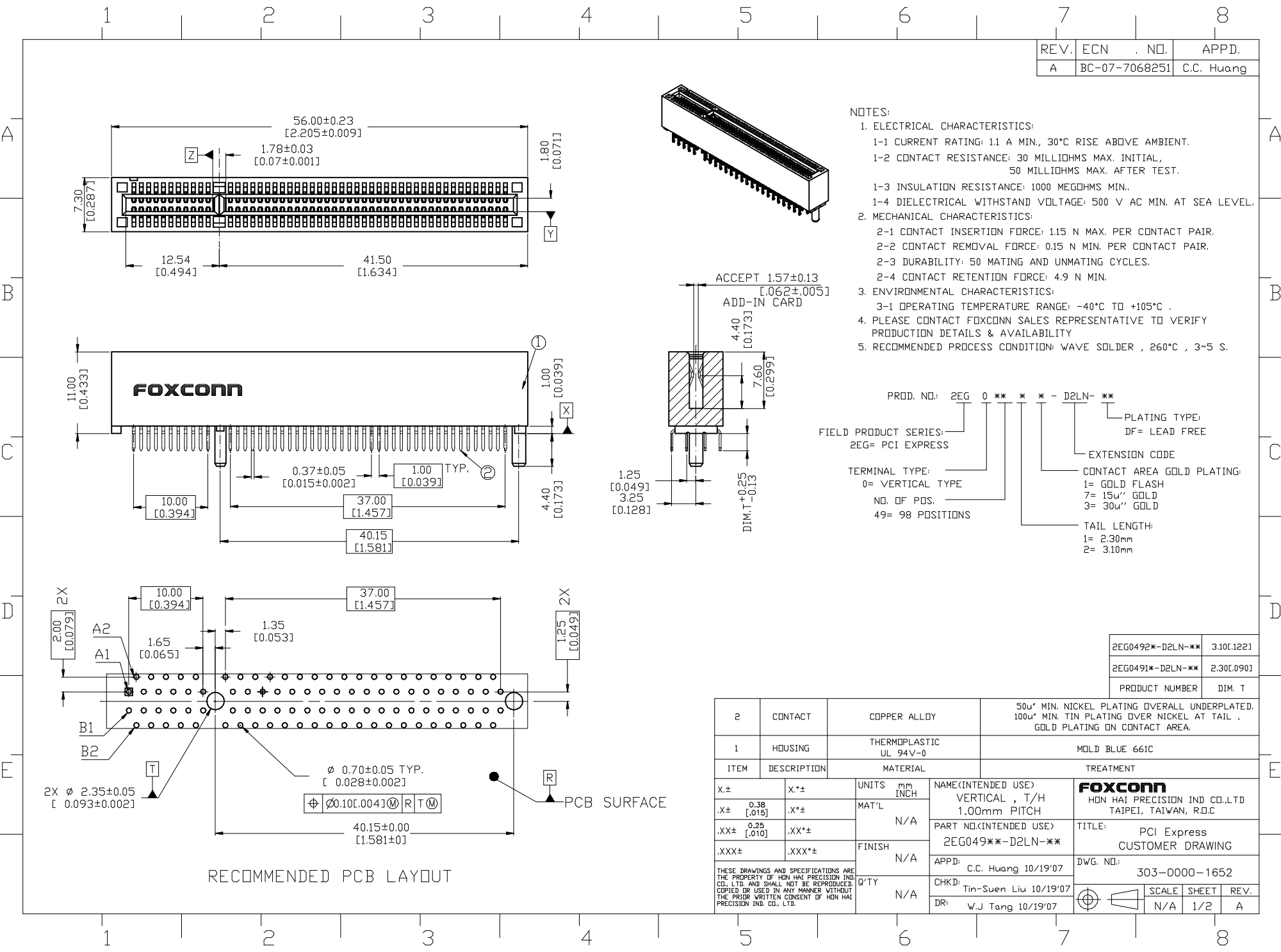
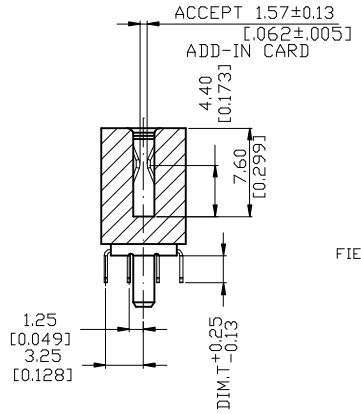


REV.	ECN	NO.	APPD.
A	BC-07-7068251		C.C. Huang



NOTES:

- ELECTRICAL CHARACTERISTICS:
  - 1-1 CURRENT RATING: 1.1 A MIN., 30°C RISE ABOVE AMBIENT.
  - 1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
  - 1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN.
  - 1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.
- MECHANICAL CHARACTERISTICS:
  - 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
  - 2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
  - 2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
  - 2-4 CONTACT RETENTION FORCE: 4.9 N MIN.
- ENVIRONMENTAL CHARACTERISTICS:
  - 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C.
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCTION DETAILS & AVAILABILITY
- RECOMMENDED PROCESS CONDITION: WAVE SOLDER, 260°C, 3-5 S.



PROD. NO.: 2EG 0 \*\* \* \* - D2LN - \*\*

FIELD PRODUCT SERIES: 2EG= PCI EXPRESS

TERMINAL TYPE: 0= VERTICAL TYPE

NO. OF POS. 49= 98 POSITIONS

PLATING TYPE: DF= LEAD FREE

EXTENSION CODE

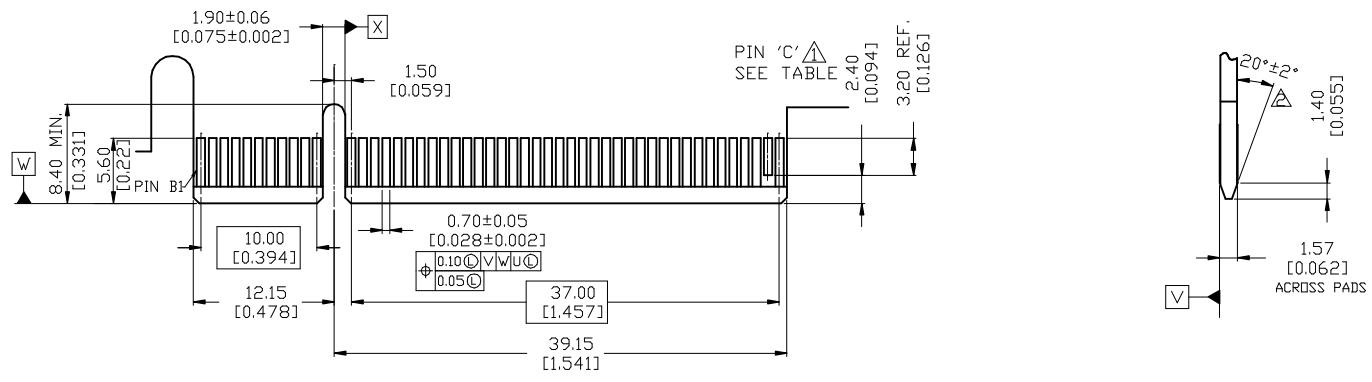
CONTACT AREA GOLD PLATING:  
1= GOLD FLASH  
7= 15μ" GOLD  
3= 30μ" GOLD

TAIL LENGTH:  
1= 2.30mm  
2= 3.10mm

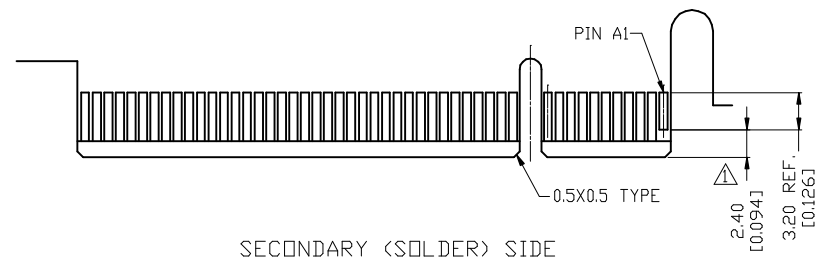
2EG0492*-D2LN-**	3.10LJ22J
2EG0491*-D2LN-**	2.30L090J
PRODUCT NUMBER	DIM. T

2	CONTACT	COPPER ALLOY	50μ" MIN. NICKEL PLATING OVERALL UNDERPLATED. 100μ" MIN. TIN PLATING OVER NICKEL AT TAIL, GOLD PLATING ON CONTACT AREA.						
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLD BLUE 661C						
ITEM	DESCRIPTION	MATERIAL	TREATMENT						
X.±	X.*±	UNITS mm INCH	<b>FOXCONN</b> HON HAI PRECISION IND. CO., LTD TAIPEI, TAIWAN, R.O.C. TITLE: PCI Express CUSTOMER DRAWING DWG. NO.: 303-0000-1652						
.X±	.X*±	MAT'L							
.XX±	.XX*±	N/A							
.XXX±	.XXX*±	FINISH							
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.		Q'TY	APPD: C.C. Huang 10/19/07 CHKD: Tin-Suen Liu 10/19/07 DR: W.J Tang 10/19/07						
			<table border="1"> <tr> <td>SCALE</td> <td>SHEET</td> <td>REV.</td> </tr> <tr> <td>N/A</td> <td>1/2</td> <td>A</td> </tr> </table>	SCALE	SHEET	REV.	N/A	1/2	A
SCALE	SHEET	REV.							
N/A	1/2	A							

RECOMMENDED PCB LAYOUT



← I/O PANEL DIRECTION  
PRIMARY (COMPONENT) SIDE



SECONDARY (SOLDER) SIDE  
ADD-IN CARD EDGE-FINGER DIMENSIONS

NOTES:  
 1. AND TIE PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND 'C'.  
 2. CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

X±	X*±	UNITS	mm INCH	NAME<INTENDED USE> VERTICAL , T/H 1.00mm PITCH	<b>FOXCONN</b> HON HAI PRECISION IND CO.,LTD TAIPEI, TAIWAN, R.O.C
.X±	.X*±	MAT'L	N/A	PART NO.<INTENDED USE> 2EG049**~D2LN~**	TITLE: PCI Express CUSTOMER DRAWING
.XX±	.XX*±	FINISH	N/A	APPD: C.C. Huang 10/19/07	DWG. NO.: 303-0000-1652
.XXX±	.XXX*±	Q'TY	N/A	CHKD: Tin-Suen Liu 10/19/07	
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